

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary

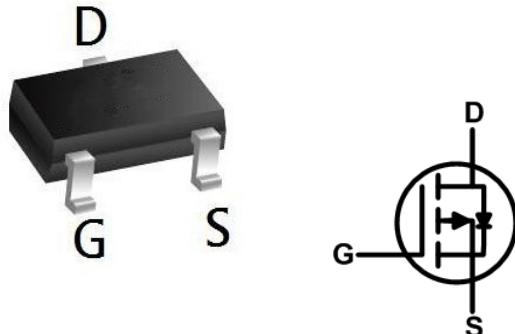
BVDSS	RDS(ON)	ID
-30V	42mΩ	-4.1 A

### Description

The XCH3401A is the high cell density trenched P-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The XCH3401A meet the RoHS and Green Product requirement with full function reliability approved.

### SOT 23 Pin Configurations



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current	-4.1	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current	-3.6	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-20	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.4	W
P <sub>D</sub> @T <sub>A</sub> =70°C	Total Power Dissipation <sup>3</sup>	0.9	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	125	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤ 10s)	---	85	°C/W

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	-0.014	---	$\text{V}/^{\circ}\text{C}$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-3\text{A}$	---	42	55	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-3\text{A}$	---	54	68	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-0.5	---	-1.2	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	2.6	---	$\text{mV}/^{\circ}\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^{\circ}\text{C}$	---	---	-1	$\text{uA}$
		$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^{\circ}\text{C}$	---	---	-5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_{\text{D}}=-3\text{A}$	---	5.6	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-3\text{A}$	---	11.9	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	1.8	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	3	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $R_{\text{G}}=3.3\Omega$ , $I_{\text{D}}=-3\text{A}$	---	6.6	---	$\text{ns}$
$T_r$	Rise Time		---	27.8	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	46.2	---	
$T_f$	Fall Time		---	20.6	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	920	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	73	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	71	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-4.3	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

### Typical Characteristics

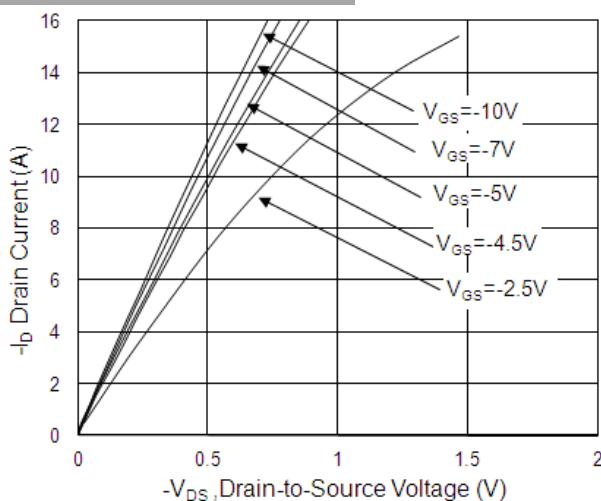


Fig.1 Typical Output Characteristics

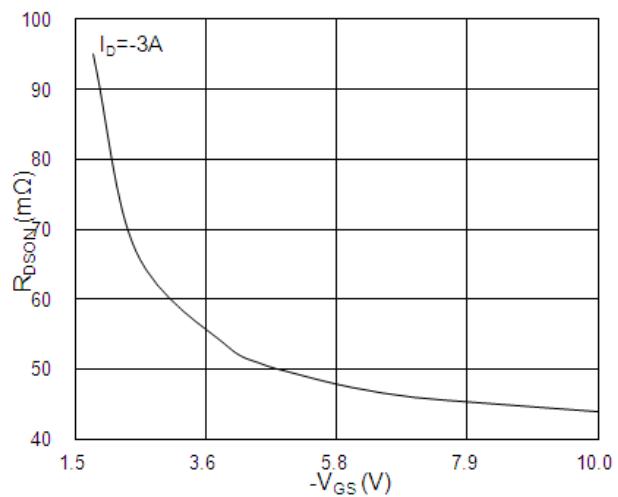


Fig.2 On-Resistance vs. G-S Voltage

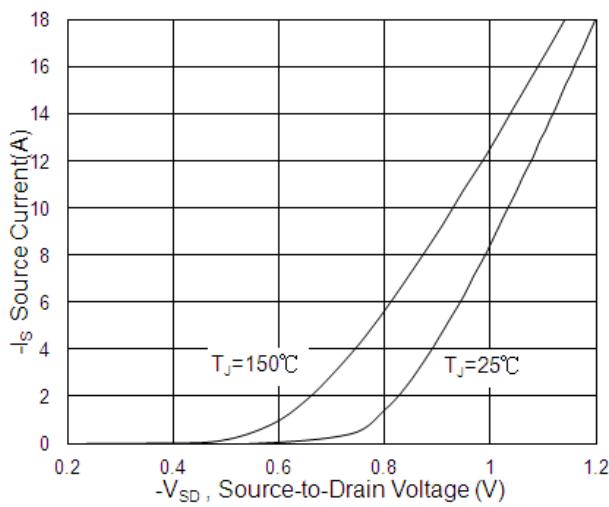


Fig.3 Forward Characteristics Of Reverse

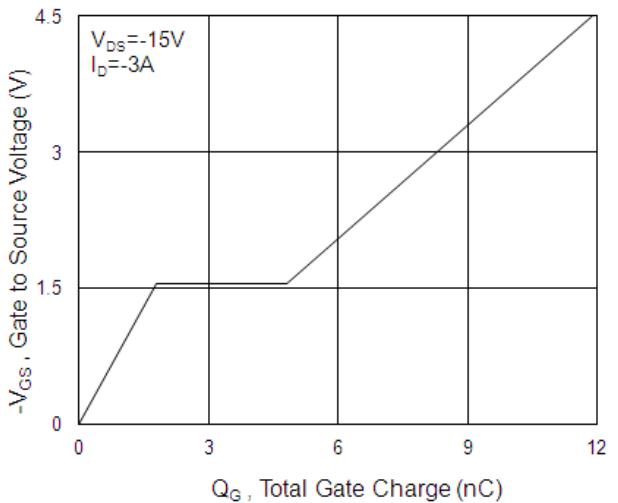


Fig.4 Gate-Charge Characteristics

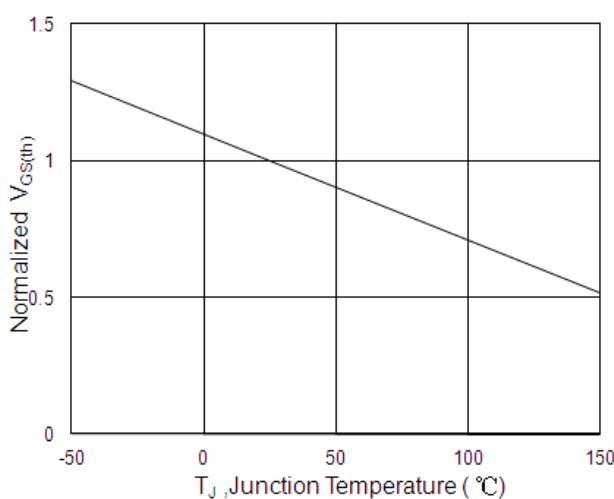


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

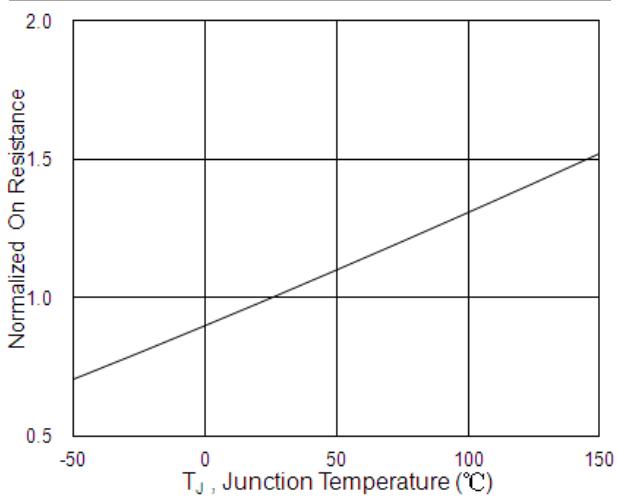
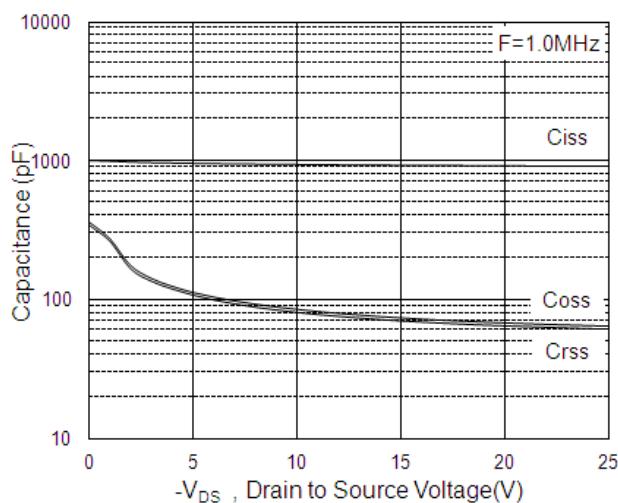
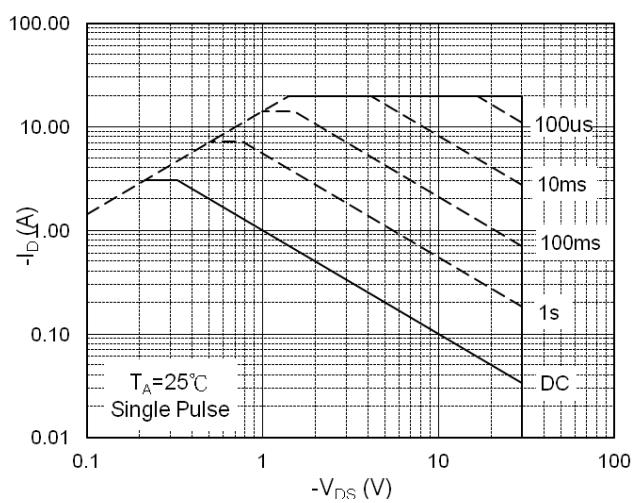


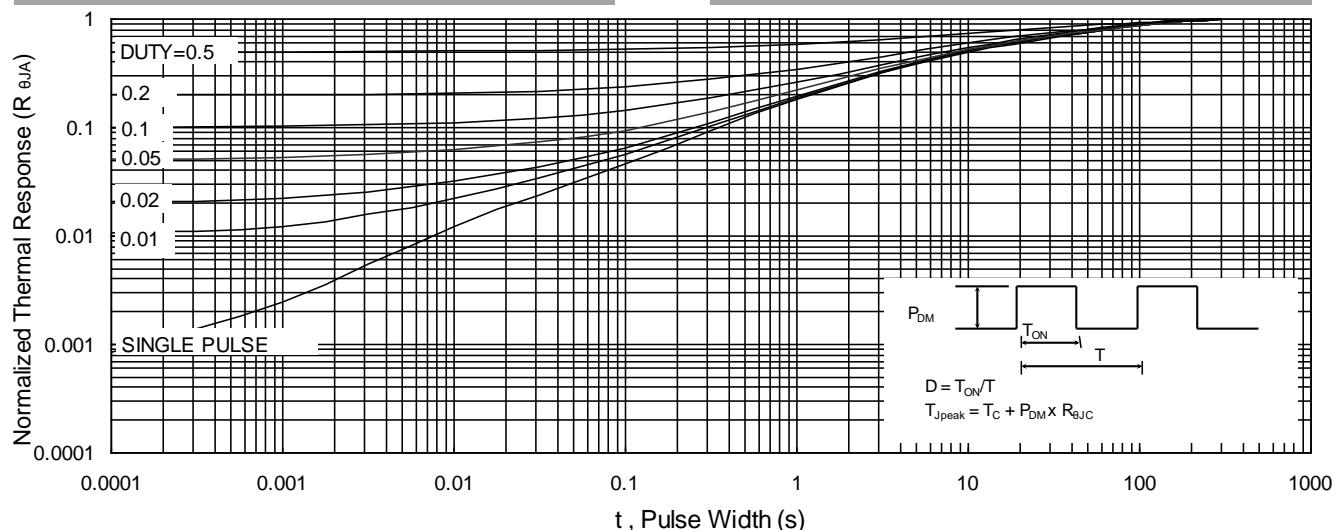
Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$



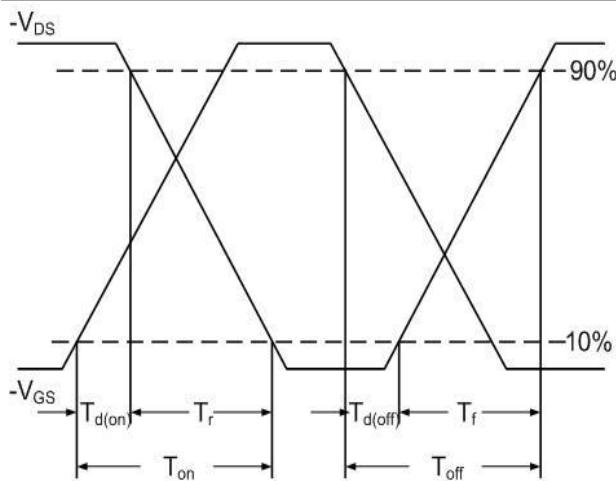
**Fig.7 Capacitance**



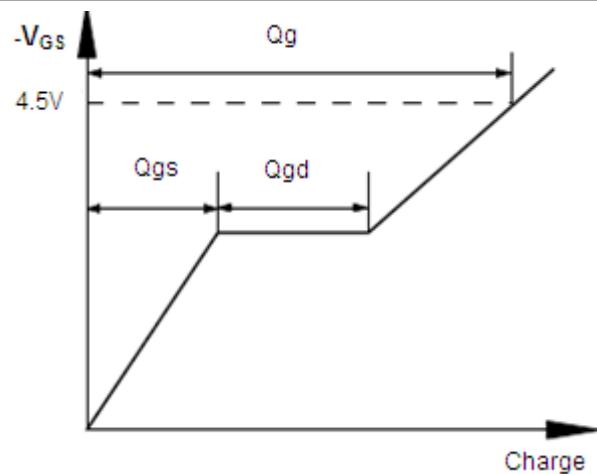
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

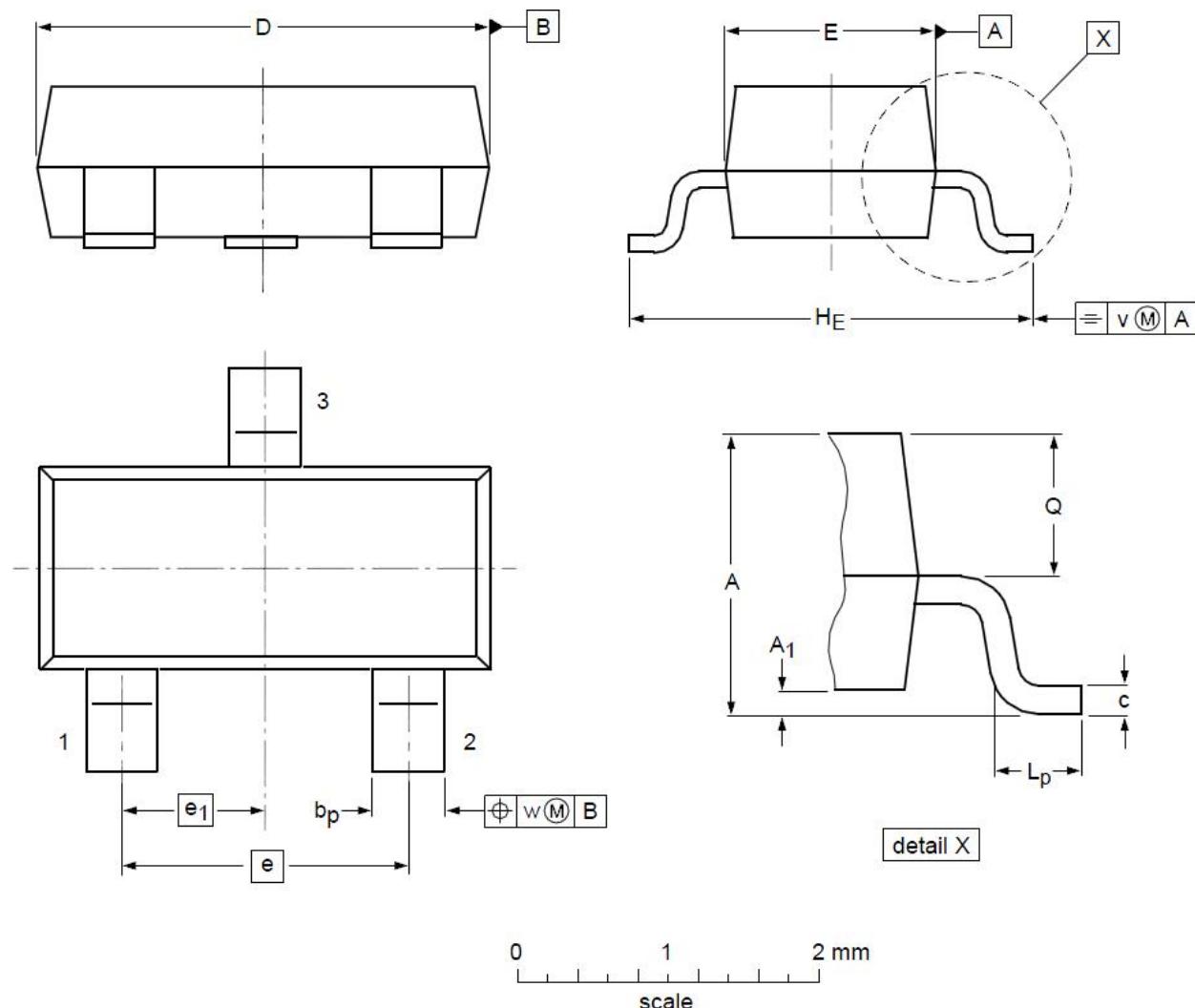


**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**

### SOT23 Mechanical Data



**DIMENSIONS ( unit : mm )**

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
<b>A</b>	0.90	1.01	1.15	<b>A<sub>1</sub></b>	0.01	0.05	0.10
<b>b<sub>p</sub></b>	0.30	0.42	0.50	<b>c</b>	0.08	0.13	0.15
<b>D</b>	2.80	2.92	3.00	<b>E</b>	1.20	1.33	1.40
<b>e</b>	--	1.90	--	<b>e<sub>1</sub></b>	--	0.95	--
<b>H<sub>E</sub></b>	2.25	2.40	2.55	<b>L<sub>p</sub></b>	0.30	0.42	0.50
<b>Q</b>	0.45	0.49	0.55	<b>v</b>	--	0.20	--
<b>w</b>	--	0.10	--				